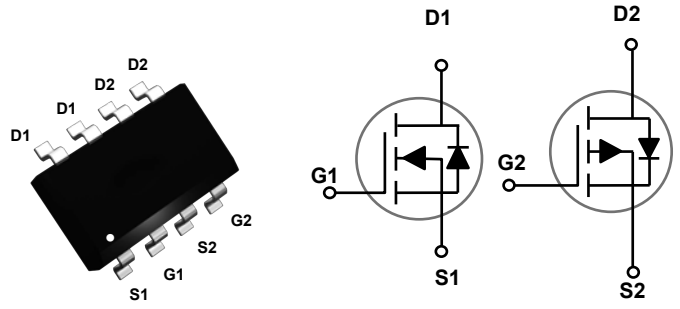


Main Product Characteristics

Channel	N-Channel	P-Channel
BV_{DSS}	30V	-30V
$R_{DS(ON)}$	20m Ω (Max.)	50m Ω (Max.)
I_D	8A	-5.5A



SOP-8

Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFQ3712 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating		Units
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Drain Current-Continuous ($T_A=25^\circ\text{C}$)	I_D	8	-5.5	A
Drain Current-Continuous ($T_A=70^\circ\text{C}$)		6.4	-4.4	A
Drain Current-Pulsed ^{1,5}	I_{DM}	32	-22	A
Single Pulse Avalanche Energy ^{2,6}	E_{AS}	14	5	mJ
Single Pulse Avalanche Current ²	I_{AS}	17	10	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	2		W
Power Dissipation-Derate above 25°C		0.016		W/ $^\circ\text{C}$
Max. Thermal Resistance Junction to Ambient	$R_{\theta JA}$	62.5		$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55 to +150		$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150		$^\circ\text{C}$

N-Channel Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	-	-	10	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A	-	15	20	mΩ
		V _{GS} =4.5V, I _D =5A	-	21	30	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	1.2	1.5	2.5	V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		-	-4	-	mV/°C
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =3A	-	3	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q _g	V _{DS} =15V, V _{GS} =4.5V, I _D =8A	-	4.1	6	nC
Gate-Source Charge ^{3,4}	Q _{gs}		-	1	1.4	
Gate-Drain Charge ^{3,4}	Q _{gd}		-	2.1	4	
Turn-On Delay Time ^{3,4}	t _{d(on)}	V _{DD} =15V, V _{GS} =10V, R _G =6Ω, I _D =1A	-	2.8	5	nS
Rise Time ^{3,4}	t _r		-	7.2	14	
Turn-Off Delay Time ^{3,4}	t _{d(off)}		-	15.8	30	
Fall Time ^{3,4}	t _f		-	4.6	9	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1MHz	-	345	500	pF
Output Capacitance	C _{oss}		-	55	80	
Reverse Transfer Capacitance	C _{rss}		-	32	55	
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	3.2	6.4	Ω
Drain-Source Ratings and Characteristics						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	-	-	8	A
Pulsed Source Current	I _{SM}		-	-	16	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25°C	-	-	1	V
Reverse Recovery Time	t _{rr}	V _R =30V, I _S =4A, di/dt=100A/μs, T _J =25°C	-	110	-	nS
Reverse Recovery Charge	Q _{rr}		-	145	-	nC

Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=17A, R_G=25Ω, starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300uS, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

P-Channel Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250uA	-30	-	-	V
BV _{DSS} Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25°C, I _D =-1mA	-	-0.03	-	V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V, T _J =25°C	-	-	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =125°C	-	-	-10	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-5A	-	40	50	mΩ
		V _{GS} =-4.5V, I _D =-3A	-	65	90	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.5	V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		-	4	-	mV/°C
Forward Transconductance	g _{fs}	V _{DS} =-10V, I _D =-3A	-	3.5	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{7,8}	Q _g	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-3A	-	5.1	7	nC
Gate-Source Charge ^{7,8}	Q _{gs}		-	2	3	
Gate-Drain Charge ^{7,8}	Q _{gd}		-	2.2	4	
Turn-On Delay Time ^{7,8}	t _{d(on)}	V _{DD} =-15V, V _{GS} =-10V, R _G =6Ω, I _D =-1A	-	3.4	6	nS
Rise Time ^{7,8}	t _r		-	10.8	21	
Turn-Off Delay Time ^{7,8}	t _{d(off)}		-	26.9	51	
Fall Time ^{7,8}	t _f		-	6.9	13	
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, F=1MHz	-	560	810	pF
Output Capacitance	C _{oss}		-	55	80	
Reverse Transfer Capacitance	C _{rss}		-	40	60	
Drain-Source Ratings and Characteristics						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	-	-	-5.5	A
Pulsed Source Current	I _{SM}		-	-	-11	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-1A, T _J =25°C	-	-	-1	V
Reverse Recovery Time	t _{rr}	V _R =-30V, I _S =-3A, di/dt=100A/μs, T _J =25°C	-	155	-	nS
Reverse Recovery Charge	Q _{rr}		-	250	-	nC

Notes:

5. Repetitive rating: Pulsed width limited by maximum junction temperature.
6. V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-10A, R_G=25Ω, starting T_J=25°C.
7. The data tested by pulsed, pulse width ≤ 300uS, duty cycle ≤ 2%.
8. Essentially independent of operating temperature.

N-Channel Typical Electrical and Thermal Characteristic Curves

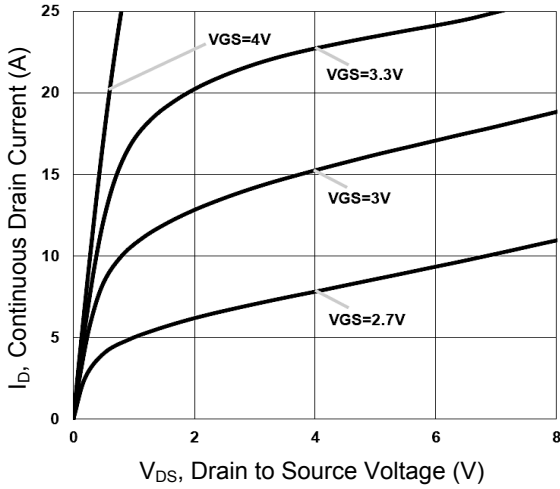


Figure 1. Typical Output Characteristics

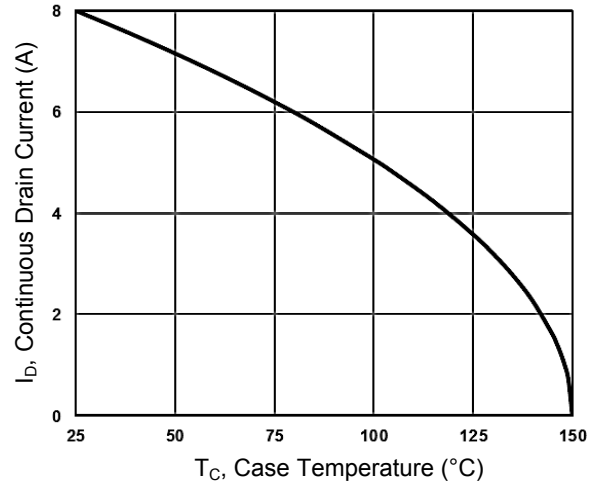


Figure 2. Continuous Drain Current vs. T_C

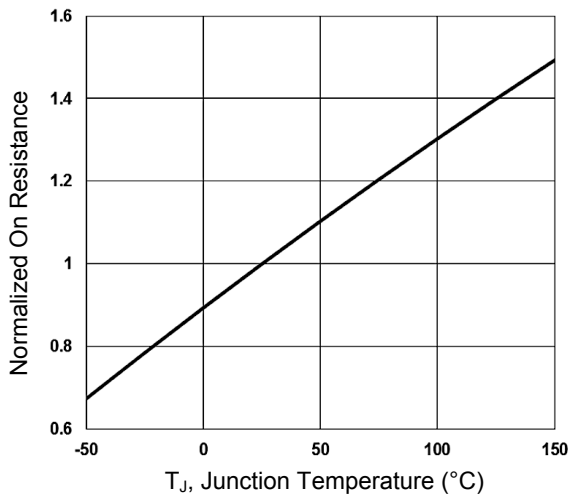


Figure 3. Normalized $R_{DS(ON)}$ vs. T_J

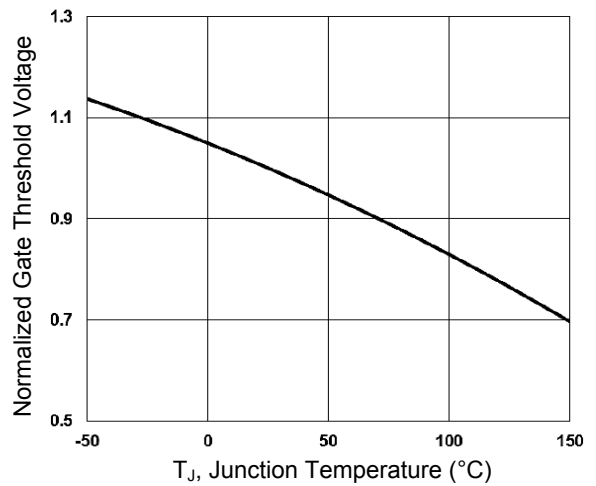


Figure 4. Normalized V_{th} vs. T_J

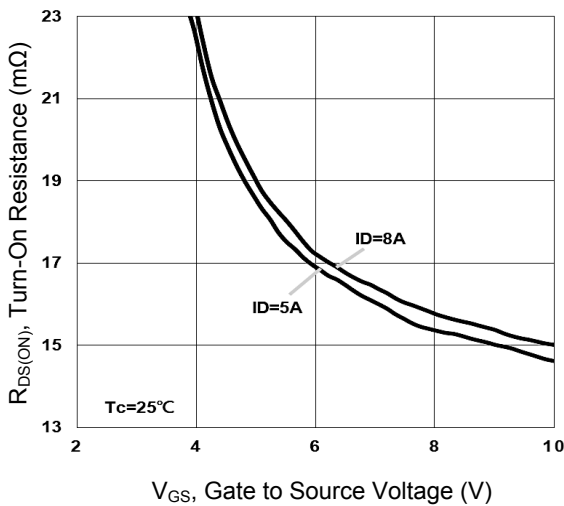


Figure 5. Turn-On Resistance vs. V_{GS}

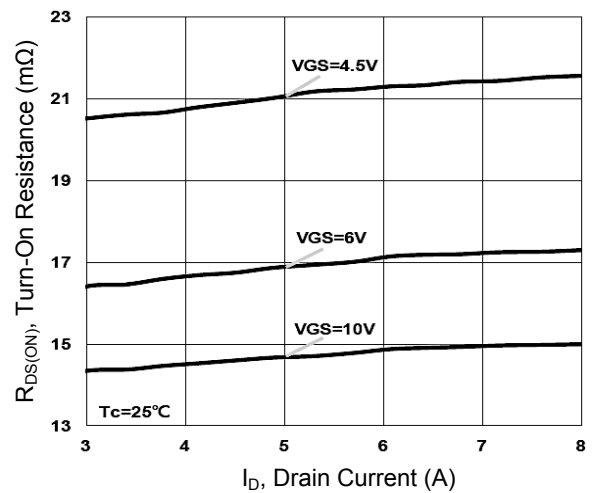


Figure 6. Turn-On Resistance vs. I_D

N-Channel Typical Electrical and Thermal Characteristic Curves

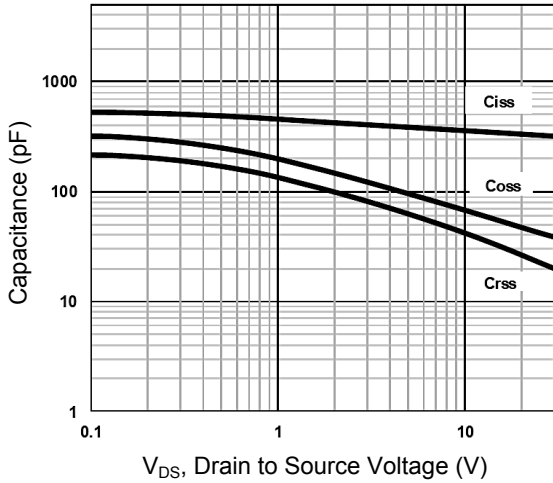


Figure 7. Capacitance Characteristics

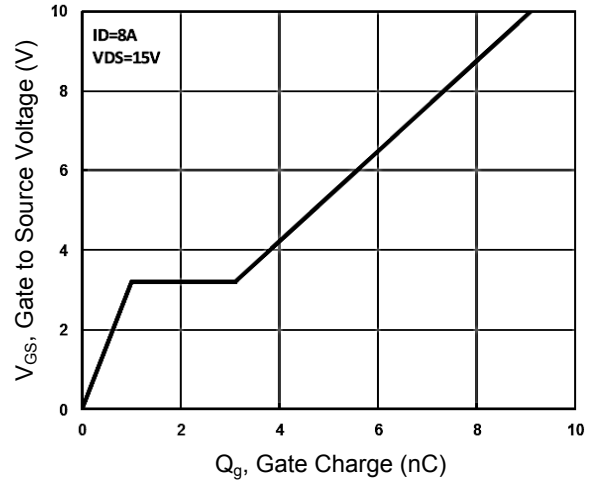


Figure 8. Gate Charge Characteristics

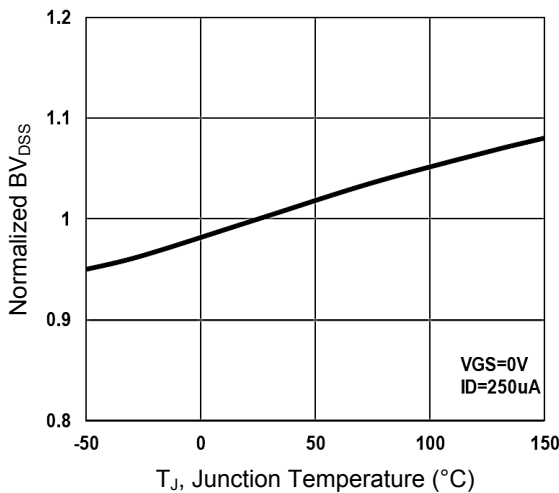


Figure 9. Normalized BV_{DS} vs. T_J

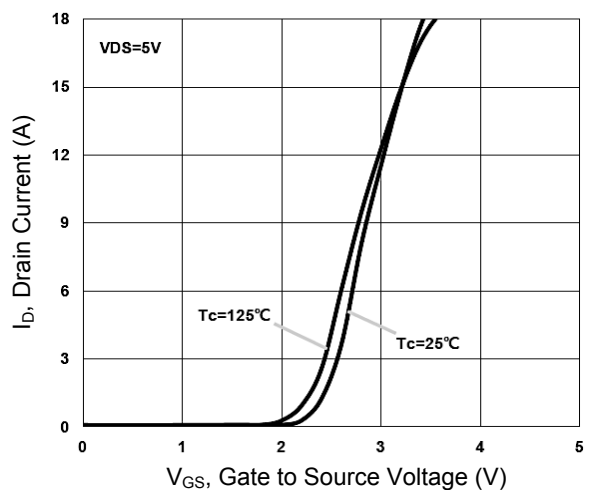


Figure 10. Transfer Characteristics

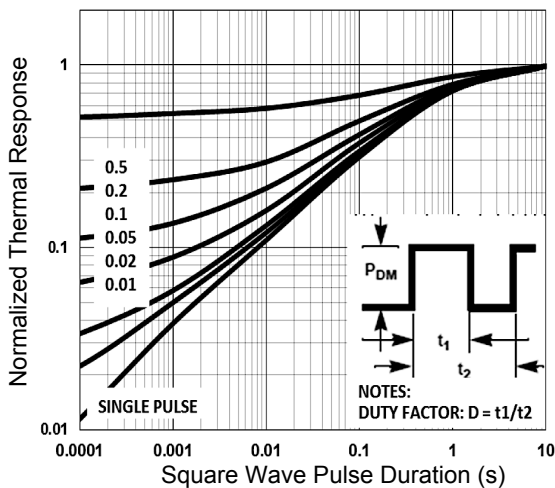


Figure 11. Normalized Transient Impedance

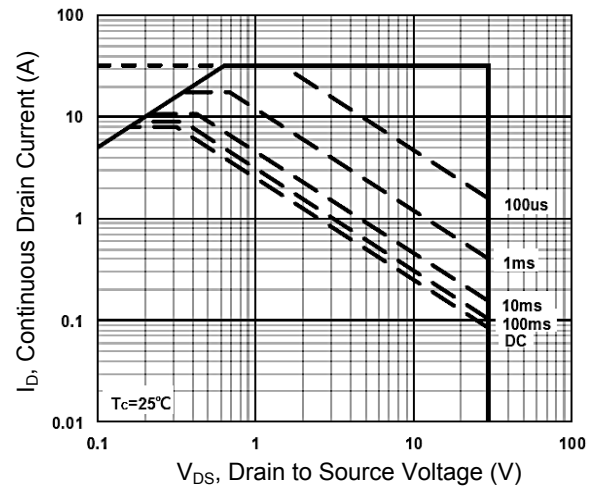


Figure 12. Maximum Safe Operation Area

P-Channel Typical Electrical and Thermal Characteristic Curves

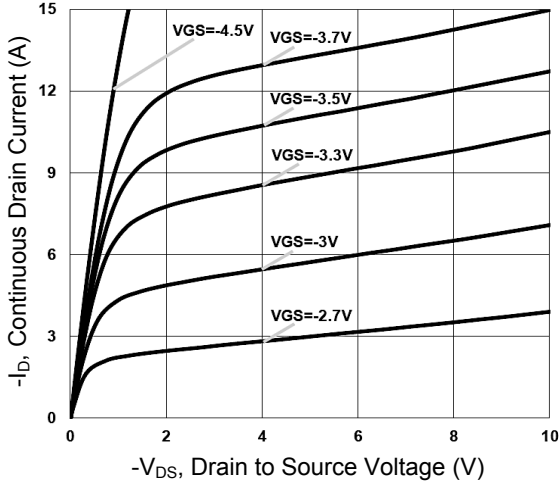


Figure 1. Typical Output Characteristics

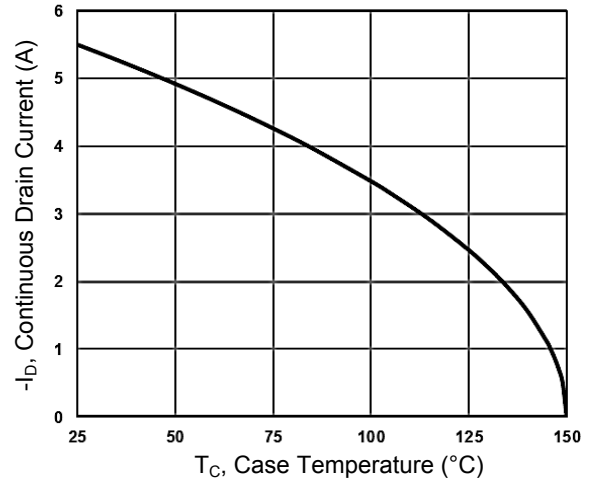


Figure 2. Continuous Drain Current vs. T_C

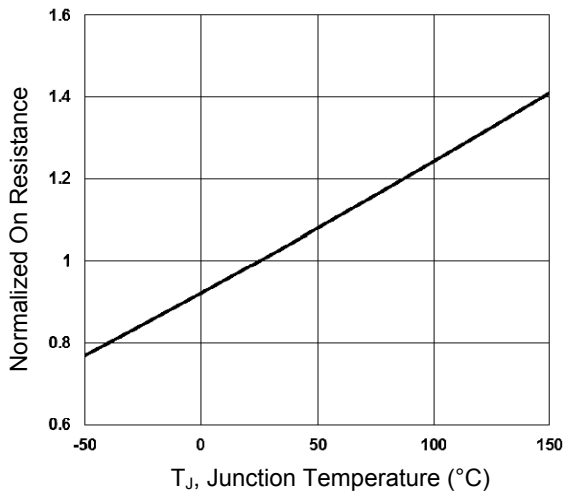


Figure 3. Normalized $R_{DS(ON)}$ vs. T_J

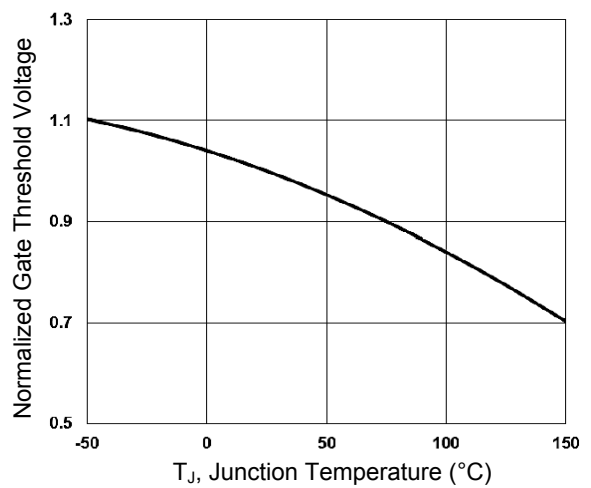


Figure 4. Normalized V_{th} vs. T_J

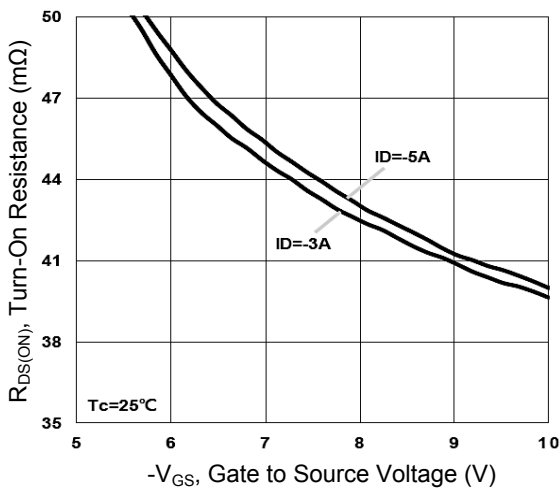


Figure 5. Turn-On Resistance vs. V_{GS}

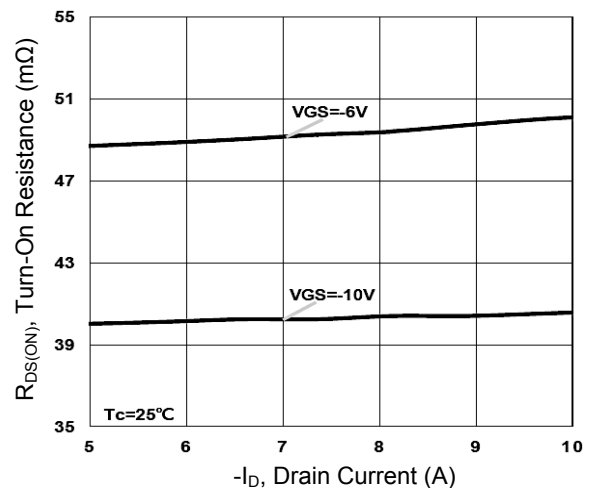


Figure 6. Turn-On Resistance vs. I_D

P-Channel Typical Electrical and Thermal Characteristic Curves

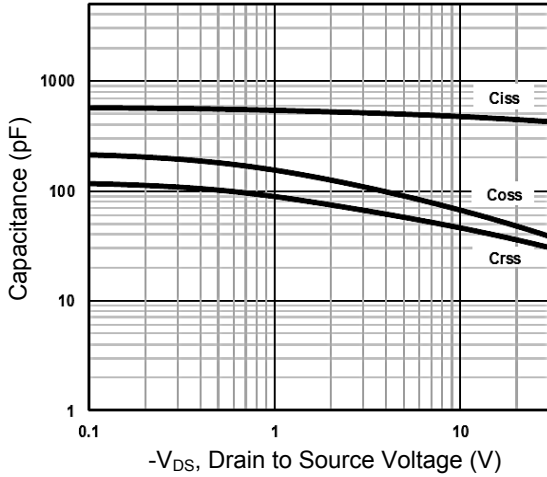


Figure 7. Capacitance Characteristics

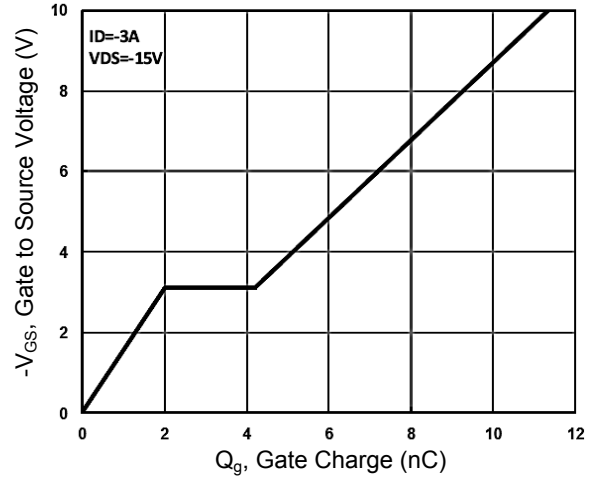


Figure 8. Gate Charge Characteristics

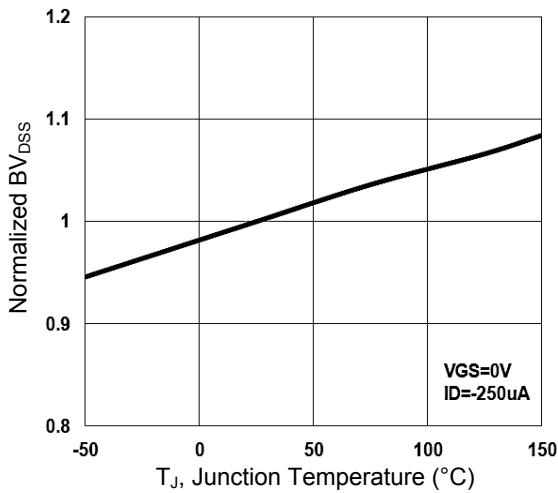


Figure 9. Normalized BV_{DS} vs. T_J

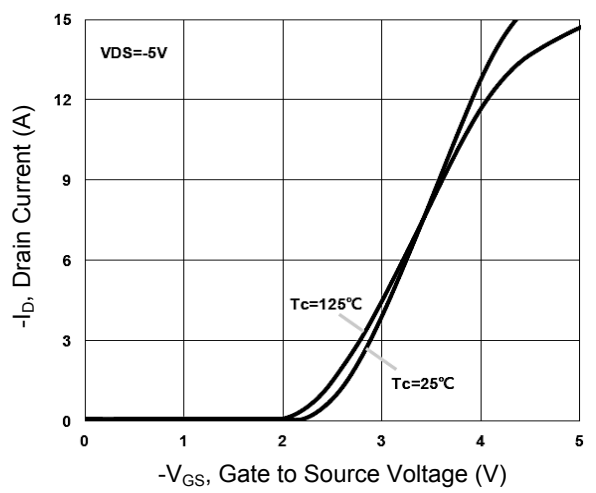


Figure 10. Transfer Characteristics

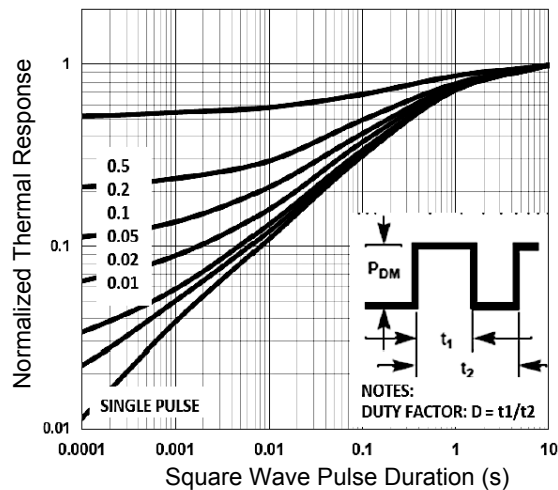


Figure 11. Normalized Transient Impedance

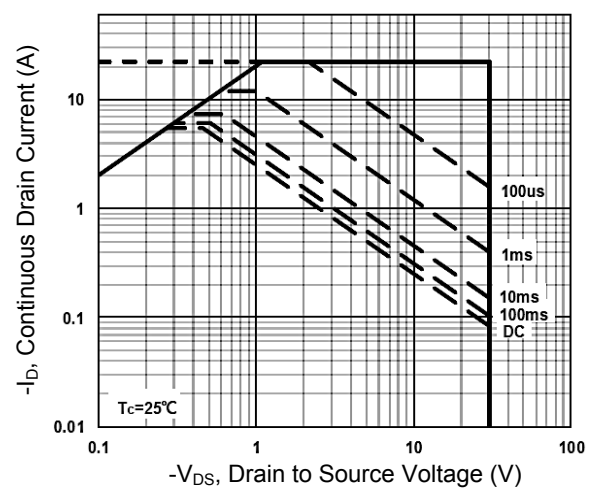
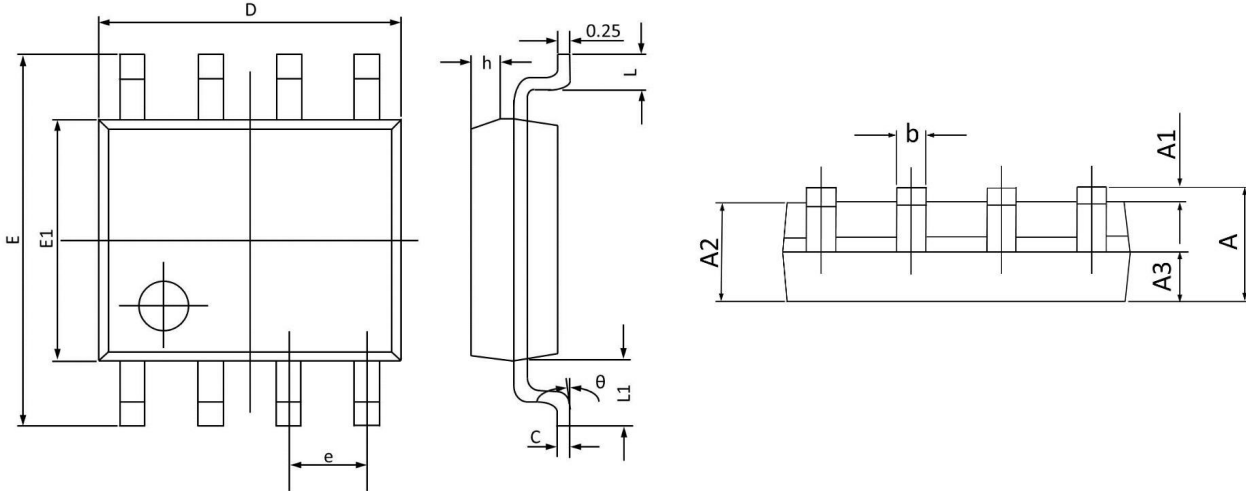


Figure 12. Maximum Safe Operation Area

Package Outline Dimensions (SOP-8)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
C	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270 BSC		0.050 BSC	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050 BSC		0.041 BSC	
θ	0°	8°	0°	8°

Order Information

Device	Package	Marking	Carrier	Quantity
SSFQ3712	SOP-8	DS3712	Tape & Reel	3,000 Pcs / Reel

For more information, please contact us at: inquiry@goodarksemi.com